

LISTING OF CLAIMS

The listing of claims provided below replaces all prior versions, and listings, of claims in the application.

5 1. (Currently Amended) A conditioning apparatus for use in a chemical mechanical planarization (CMP) system, comprising:

a conditioning substrate;

a holder configured to hold the conditioning substrate;

a shaft connected to the holder; and

10 ~~rotation mechanics capable of rotating the shaft causing the holder and the conditioning substrate to be rotated with the shaft; and~~

oscillation mechanics capable of moving ~~a position of the shaft within a region defined by a peripheral boundary that is less than and within an outer periphery of the conditioning substrate~~ in an oscillatory manner such that the conditioning substrate is
15 moved about a centroid of the conditioning substrate.

2. (Currently Amended) The ~~[[A]]~~ conditioning apparatus for use in a CMP system as recited in claim 1, wherein the oscillation mechanics are configured to move ~~the position of the shaft~~ and conditioning substrate attached thereto in a specific
20 oscillation pattern within the region defined by the peripheral boundary about the centroid of the conditioning substrate.

3. (Currently Amended) The ~~[[A]]~~ conditioning apparatus for use in a CMP system as recited in claim 2, wherein the specific oscillation pattern is represented as one
25 of an orbital oscillation pattern and a linear oscillation pattern.

4. (Currently Amended) The ~~[[A]]~~ conditioning apparatus for use in a CMP system as recited in claim 1, wherein the oscillation mechanics are configured to move the ~~position of the shaft and conditioning substrate attached thereto~~ in a random pattern ~~within the region defined by the peripheral boundary~~ about the centroid of the
5 conditioning substrate.

5. (Cancelled)

6. (Currently Amended) The ~~[[A]]~~ conditioning apparatus for use in a CMP
10 system as recited in claim 1, further comprising:

a positioning arm configured to engage the shaft, the positioning arm capable of sweeping the conditioning substrate over a working surface of a CMP pad in tandem with operation of the ~~rotation mechanics and the~~ oscillation mechanics.

15 7-12. (Cancelled)

13. (Currently Amended) A conditioning apparatus for use in a chemical mechanical planarization (CMP) system, comprising:

a conditioning substrate having an active side and a backside; and
20 a conditioning substrate backing capable of defining a differential pressure distribution across ~~capable of being applied to~~ the backside of the conditioning substrate, whereby different pressures can be applied to specific regions of the backside of the
conditioning substrate.

25 14. (Currently Amended) The ~~[[A]]~~ conditioning apparatus for use in a CMP system as recited in claim 13, wherein the conditioning substrate backing is configured as

a fluid conditioning substrate backing, the fluid conditioning substrate backing being defined by a number of fluid chambers, each of the number of fluid chambers capable of applying a specific pressure to the backside of the conditioning substrate.

5 15. (Currently Amended) The ~~[[A]]~~A conditioning apparatus for use in a CMP system as recited in claim 14, wherein the fluid conditioning substrate backing is configured to allow the differential pressure distribution to be controlled during a CMP process.

10 16. (Cancelled)

 17. (Currently Amended) The ~~[[A]]~~A conditioning apparatus for use in a CMP system as recited in claim 13, wherein the conditioning substrate is configured to transfer the differential pressure distribution from the backside of the conditioning substrate to the
15 active side of the conditioning substrate.

 18. (Currently Amended) The ~~[[A]]~~A conditioning apparatus for use in a CMP system as recited in claim 13, further comprising:

 a holder configured to receive and hold both the conditioning substrate backing
20 and the conditioning substrate;

 a shaft being connected to the holder; and

 rotation mechanics capable of rotating the shaft causing the holder, the conditioning substrate backing, and the conditioning substrate to be rotated with the shaft.

25 19-22. (Cancelled)

23. (New) The conditioning apparatus for use in a CMP system as recited in claim 1, further comprising:

rotation mechanics capable of rotating the shaft causing the holder and the conditioning substrate to be rotated with the shaft.

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24. (New) The conditioning apparatus for use in a CMP system as recited in claim 1, wherein the centroid of the conditioning substrate represents a point from which all distances to an outer periphery of the conditioning substrate sum to zero.

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25. (New) A conditioning apparatus for use in a chemical mechanical planarization (CMP) system, comprising:

a conditioning substrate;

a holder configured to hold the conditioning substrate;

a shaft connected to the holder;

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rotation mechanics capable of rotating the shaft causing the holder and the conditioning substrate to be rotated with the shaft; and

oscillation mechanics capable of moving a position of the shaft within a region defined by a circular peripheral boundary having a radius that is less than ten percent of a radius defining the outer periphery of the conditioning substrate.

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26. (New) A conditioning apparatus for use in a chemical mechanical planarization (CMP) system, comprising:

a conditioning substrate having an active side and a backside; and

a conditioning substrate backing capable of defining a differential pressure distribution across the backside of the conditioning substrate, wherein the conditioning substrate backing is configured as a solid conditioning substrate backing, the solid

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conditioning substrate backing being defined by a number of material regions being differentiated by spring constant values, each of the number of material regions capable of applying a specific pressure to the backside of the conditioning substrate.